

## Amendments to the Specification

**The Paragraph beginning at Page 1, lines 8-38, through to Page 2, lines 1-4, are to be amended as follows:**

### CROSS-REFERENCE TO CO-PENDING APPLICATIONS

The following applications have been filed by the Applicant simultaneously with the present application:

10/760230	10/760225	10/760224
10/760242	10/760228	<del>6,944,970</del> 10/760250
10/760215	10/760256	10/760257
10/760240	10/760251	10/760266
<del>6,920,704</del> 10/760239	10/760193	10/760214
10/760260	10/760226	10/760269
10/760199	10/760241	10/760272
10/760273	10/760187	10/760182
10/760188	10/760218	10/760217
10/760216	10/760233	10/760246
10/760212	10/760243	10/760201
10/760185	10/760253	10/760255
10/760209	10/760208	10/760194
10/760238	10/760234	10/760235
10/760183	10/760189	10/760262
10/760232	10/760231	10/760200
10/760190	10/760191	10/760227
10/760207	10/760181	10/760254
10/760210	10/760202	10/760197
10/760198	10/760249	10/760263
<u>10/760196</u>	10/760247	10/760223
10/760264	10/760244	10/760245
10/760222	10/760248	10/760236
10/760192	10/760203	10/760204
10/760205	10/760206	10/760267
10/760270	10/760259	10/760271

10/760275	10/760274	10/760268
<del>10/760184</del> 10/760195	10/760186	10/760261
10/760258	10/760180	10/760229
10/760213	10/760219	10/760237
10/760221	10/760220	10/760211
10/760252	10/760265	

**The Paragraph beginning at Page 9, lines 7-8, are to be amended as follows:**

The ink jet printhead chip 52 (see Fig. 6) includes a silicon wafer substrate 8015.  
0.35 Micron 1 P4M 12 volt CMOS microprocessing circuitry is positioned on the silicon  
wafer substrate 8015.